

Group Art Unit: N/A

Examiner: Not Yet Assigned

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

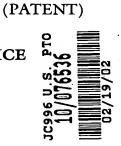
In re Patent Application of: Takeyuki Itabashi, et al.

Application No.: Not Yet Assigned

Filed: Herewith

For: ELECTROLESS COPPER PLATING SOLUTION, ELECTROLESS COPPER PLATING PROCESS AND PRODUCTION

PROCESS OF CIRCUIT BOARD



CLAIM FOR PRIORITY

Commissioner for Patents Washington, DC 20231

Dear Sir:

Applicant hereby claims priority under 35 U.S.C. 119 based on the following prior foreign application filed in the following foreign country on the date indicated:

Country	Application No.	Date
Japan	2001-048685	February 23, 2001

Application No.: Net Assigned

Cket No.: A8319.0014/P014

In support of this claim, a certified copy of the said original foreign application will be filed shortly.

Dated: February 19, 2002

Respectfully submitted,

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